

ABSTRACT

5 A polishing apparatus capable of preventing condensation on an inner surface of a transparent window provided in a polishing pad and capable of achieving accurate measuring of a film thickness is disclosed. The polishing apparatus includes: a polishing pad having a polishing surface; a polishing head configured to press a workpiece against the polishing surface; a transparent window disposed in the polishing pad; a polishing table
10 configured to support the polishing pad; an optical sensor head located below the transparent window and configured to direct light to the workpiece through the transparent window and receive reflected light from the workpiece through the transparent window; and a cooling device configured to cool a space between the transparent window and the optical sensor head.

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FIG. 3